

Delphion
INTEGRATED CIRCUIT UTILIZING Peltier Cooling Method (JP61172358A2)

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Title: JP61172358A2: INTEGRATED CIRCUIT UTILIZING Peltier Cooling Method

Country: JP Japan

Kind: A

Inventor(s): MASUBUCHI HIDEO

Applicant/Assignee
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Issued/Filed Dates:

Aug. 4, 1986 / Jan. 26, 1985

Application Number:

JP1985000013206

IPC Class:

H01L 23/38;

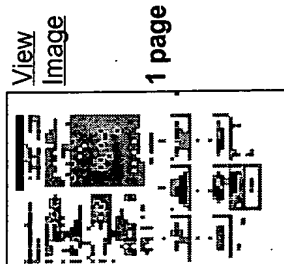
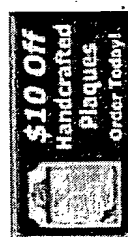
Priority Number(s):

Jan. 26, 1985 JP1985000013206

Abstract:

Purpose: To enable the fellow individual IC substrates to house in the case body at intervals one-seventh narrower than the conventional ones, and at the same time, to prevent heat from affecting the operation of the IC even though the integration degree of the IC itself is enhanced by a method wherein a cooling method according to the Peltier effect is utilized.

Constitution: This integrated circuit is formed in such a constitution that a Peltier cooling is generated at a place, where is near individual circuit main bodies 2 and is such a place as to come into contact to the interior of an element 1 or the IC element; the heat radiating part is made to locate on the upper side of the partition plates, which are about 1cm away from the main body substrate and are formed in such a way that the heat generating parts only of the individual IC circuits protrude thereto; and the heat of the heat generating parts is made to radiate at the heat radiating part. As the



cooling is one to cool locally the necessary parts in the IC, the inferiority of efficiency of the thermoelectric cooling method does not exert effect so much to the cooling effect. Moreover, when the parts other than the IC circuits are made in a heat-resisting manner, the partition plates, the fans and the heat pipes can be omitted and even when the temperature in the interior of the element rises higher than the normal one, the IC can be made to operate without being subjected to the effect functionally.

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Family:

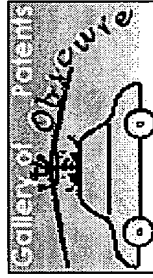
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Other Abstract Info:

DERABS G86-242635 DERG86-242635

Foreign References:

No patents reference this one



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